



Improving the Performance of your DC-DC Forward Converter using I²MOS™ MOSFET Technology

Microsemi Space Forum 2015

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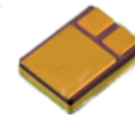
Microsemi
SPACE FORUM

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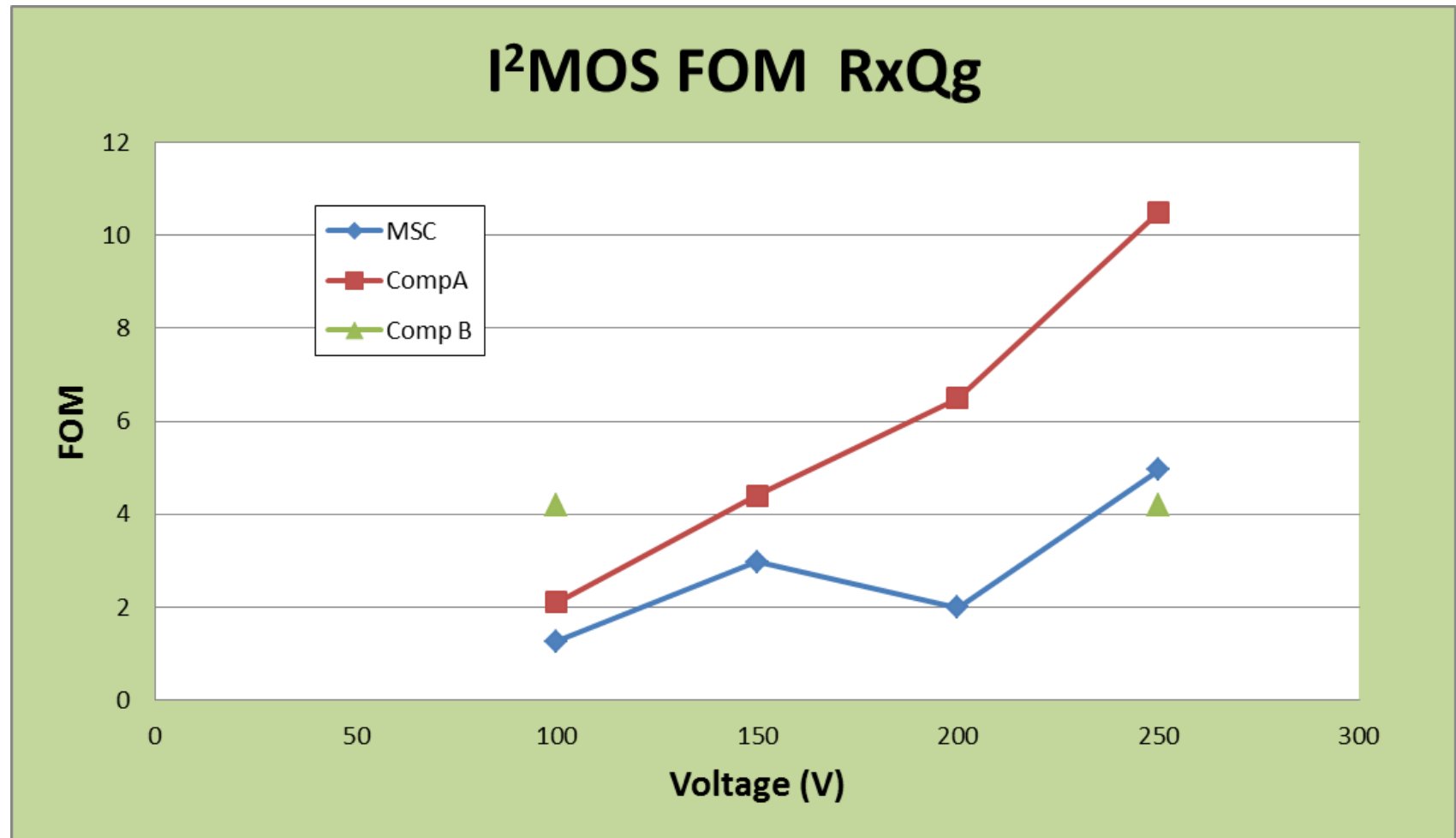
- I²MOS Advantages
- Single Event Effect Tests
- DC- DC Design performance advantages
 - Efficiency
 - Avalanche Energy
- Summary

I²MOS advantages

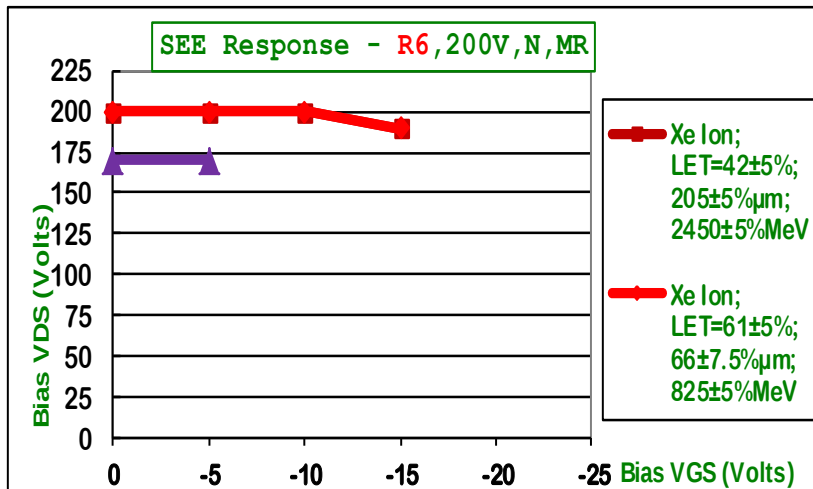
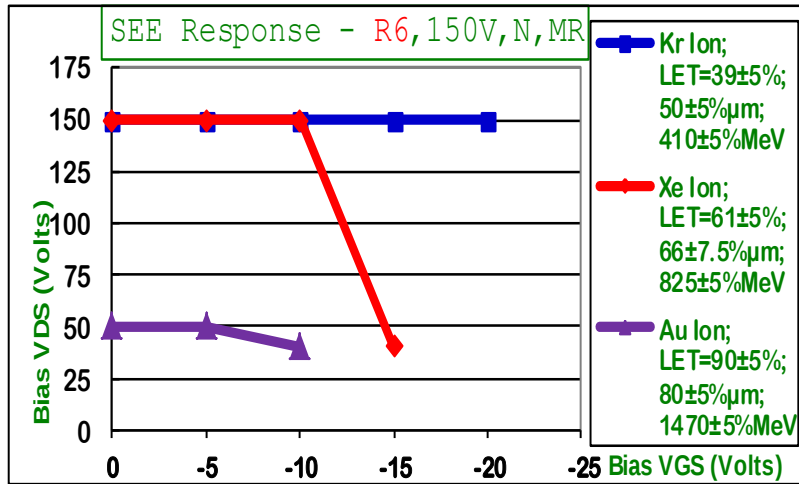
- Highest available SEE performance, 85- 90 MeV at full rated BVDss
- Highest Avalanche capability: 5X greater than competition
- TID (Total Ionizing Dose) Rating: 100Krad- 500Krad (depending on specific device)
- Commerce Rating: 9A515.e
 - Most Euro countries will not need a license!
- Competitive pricing on new designs



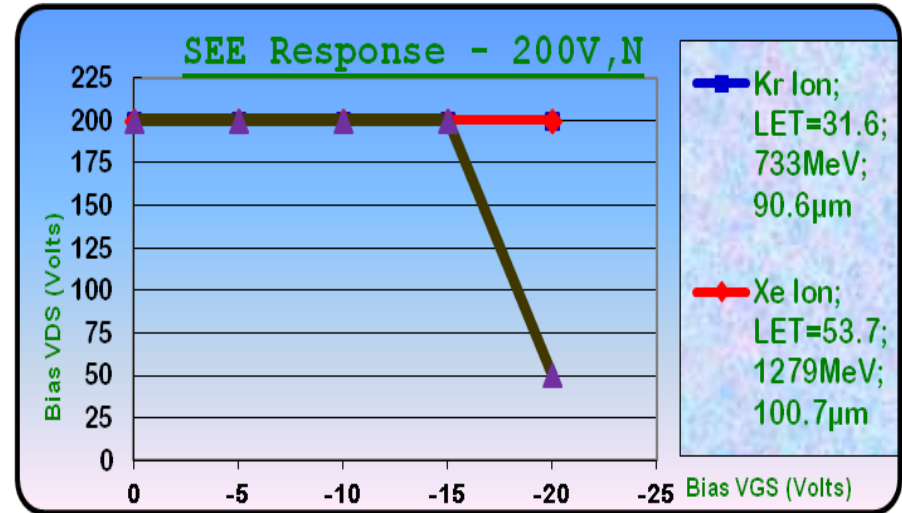
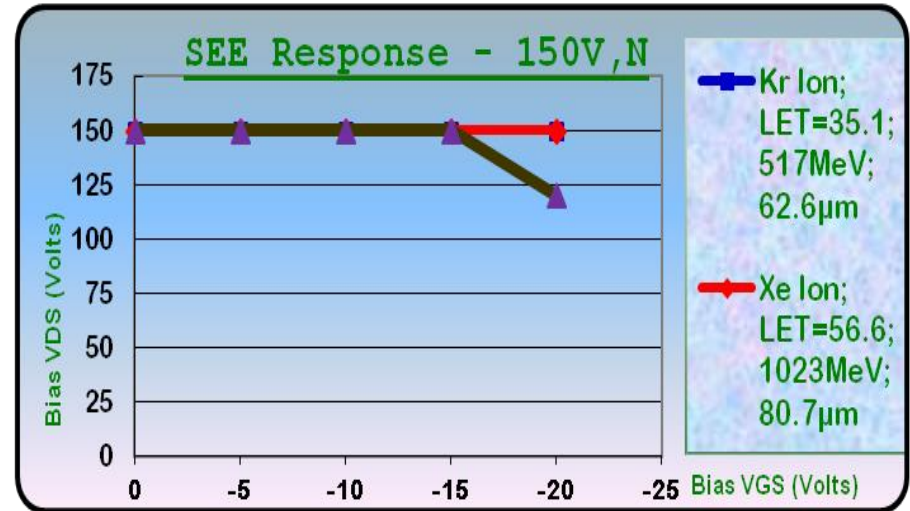
I²MOS FOM versus Competition



SEE results- Microsemi vs. Competitor



IR (R6)



Microsemi (I²MOS)

I²MOS™ MOS P/N Structure

<u>MRH</u>	<u>BVDSS/1</u> <u>0</u>	<u>Channel</u>	<u>ID @ 25C</u>	<u>Package</u>	<u>Screening</u>	<u>RAD LEVEL</u>
	(V)		(A)			
<u>MRH</u>	<u>20</u>	<u>N</u>	<u>22</u>	<u>U3</u>	<u>S</u>	<u>R</u>
Microsemi	20= 200V	N		U3= SMD0.5	S= JANS	R= 100K F= 300K
Rad- Hard	10= 100V	P		T2= TO- 39	V= JANTXV	G= 500K
MOSFET	13= 130V			T3= TO- 257	C= EDU	
	06= 60V			U5= LCC-18		
	03= 30V			C= die		

I²MOS™ Planned Products

Phase 1: I²MOS™ portfolio, N- Ch, Sz 3

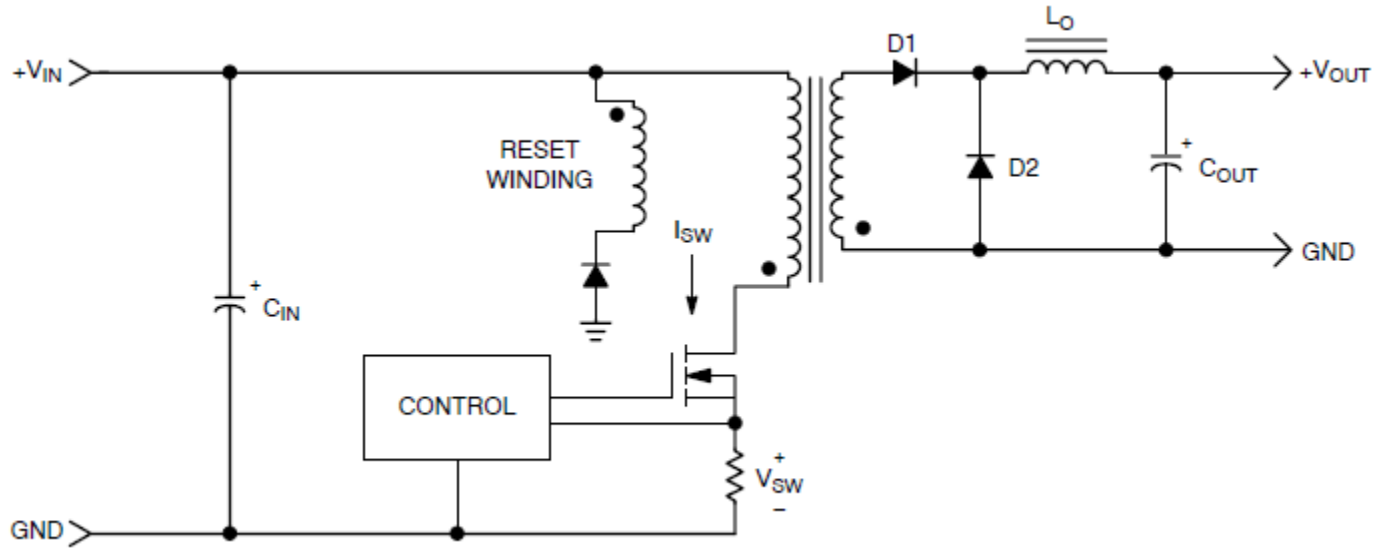
<u>Bvdss</u> (V)	<u>Similar</u> <u>JEDEC</u> <u>Number</u>	<u>Industry</u> <u>Equivalent</u>	<u>MSC p/n</u>
150	2N7589U3	IRHNJ67134	MRH15N19U3
200	2N7591U3	IRHNJ67230	MRH20N16U3
250	2N7593U3	IRHNJ67234	MRH25N15U3



Phase 2: I²MOS™ portfolio, N- Ch, Sz 5.5

<u>Bvdss</u> (V)	<u>Similar</u> <u>JEDEC</u> <u>Number</u>	<u>Industry Equivalent</u>	<u>RH2 Base MSC p/n</u>	<u>Package</u>
150	2N7582T1	IRHMS67164	MRH15N45T1	TO-254
150	2N7581U2	IRHNA67164	MRH15N56U1	SMD-2
200	2N7584T1	IRHMS67260	MRH20N45T1	TO-254
200	2N7583U2	IRHNA67260	MRH20N56U1	SMD-2
250	2N7586T1	IRHMS67264	MRH25N45T1	TO-254
250	2N7585U2	IRHNA67264	MRH25N56U1	SMD-2





Efficiency Performance of I²MOS

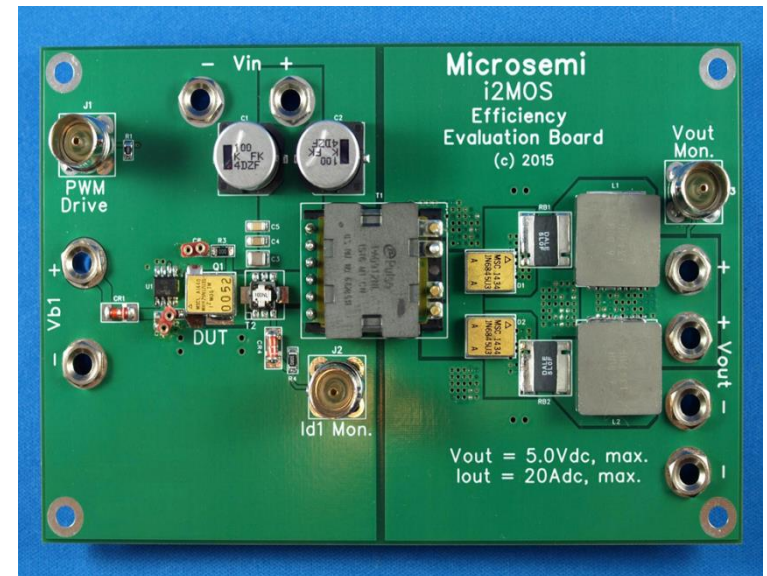
DC-DC Forward Converter (Resonant Reset Topology)
MRH25N15U3 vs. IRHNJ67234

DC-DC Criteria

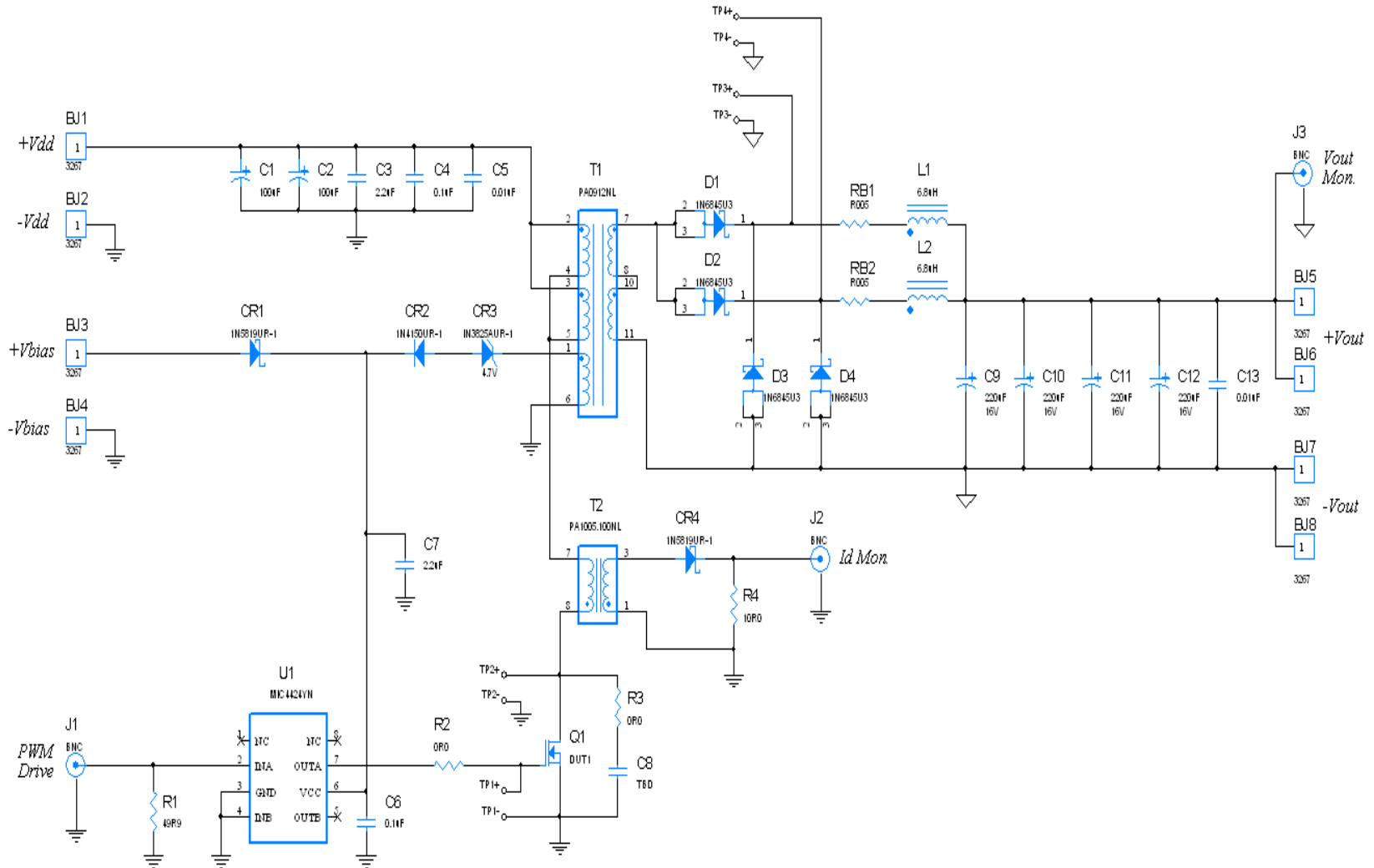
- Create a Circuit to Reveal Differences in MOSFET Power Losses
- Parallel-Inductor Isolated Forward DC-DC Converter
- Improved Efficiency
 - Resonant Transformer Reset
 - Lower DC Losses in Inductors and Schottky Rectifiers
- Use $V_{dd} = 50V_{dc}$
 - Peak of Resonant Reset Voltage Will Be: $V_{dd} + (I_d(pk) * L_m / C_r)$
 - L_m is Power Transformer Magnetizing Inductance ($\sim 120\mu H$)
 - C_r is the Resonance Capacitance = $C_{oss} \parallel C_j (N_s/N_p) * (\sim 810pF)$
 - Worst Case Resonance Peak at $f_{sw} = 350kHz$ and $V_{out} = 5.0V_{dc}$ ($\sim 120V_{pk}$)

Efficiency Test Criteria

- Voltage De- Rating= 50%
 - Use Microsemi MRH25N15U3 and IR IRHNJ67234, 250V devices.
(200V Device May Be Used For Higher Efficiency With Lower Voltage Margin.)
- 100W Maximum Output Power
 - 20A Maximum Output Current
 - 66W For $V_{out} = 3.3V_{dc}$
 - 100W For $V_{out} = 5.0V_{dc}$



Efficiency Test Circuit Schematic



Efficiency Test Circuit Features

- Circuit Used For Power Switch Efficiency Comparison:
 - Circuit Uses U3 Packages For All Power Functions
 - Small Size
 - Ease of Thermal Management
 - Output Uses Paralleled Output Stage For Increased Efficiency
 - Schottkies and Inductors Share Current ~50:50
 - DC Power Losses Reduced by ~1/4 - 1/3!
 - Optimized for $3.3\text{Vdc} < V_{\text{out}} < 5\text{Vdc}$
 - Optimized For $1\text{A} < I_{\text{out}} < 20\text{A}$
 - Optimized For $350\text{kHz} < f_{\text{sw}} < 500\text{kHz}$
 - Uses COTS Micrel MIC4424 Gate Driver IC
 - Rad-Hard Equivalents Available from Intersil

Efficiency Test Parameters

- DC Output (V_{out}) Set By Varying Input Duty Cycle

- Duty Cycle = Desired $V_{out} * (N_s/N_p) / V_{dd}$

- Efficiency:

$$\eta = P_{out} / (P_{in} + P_{bias}) = (V_{out} * I_{out}) / ((V_{dd} * I_{dd}) + (V_{bias} * I_{bias}))$$

I_{out} = Set, Varied from 1A to 20A

V_{dd} = Set, Constant = 50Vdc

V_{bias} = Set, Constant = 12Vdc

V_{out} is Set By Varying the Input Duty Cycle

I_{dd} and I_{bias} Are Measured at Each Operating Point

MOSFET Losses

- Key Contributors to Power MOSFET Switch Losses:
 - DC Losses: $I_d(\text{rms})^2 * R_{ds}(\text{on}) * D$
 - AC Losses: Gate + Switching
 - Gate Input Losses: $Q_{gt} * V_{bias} * f_{sw}$
 - Drain Switching Losses: $\sim V_{dd} * I_d(\text{rms}) * (t_r + t_f) * f_{sw} / 2$
 $+ (C_{oss} * V_{dd}^2 * f_{sw})$

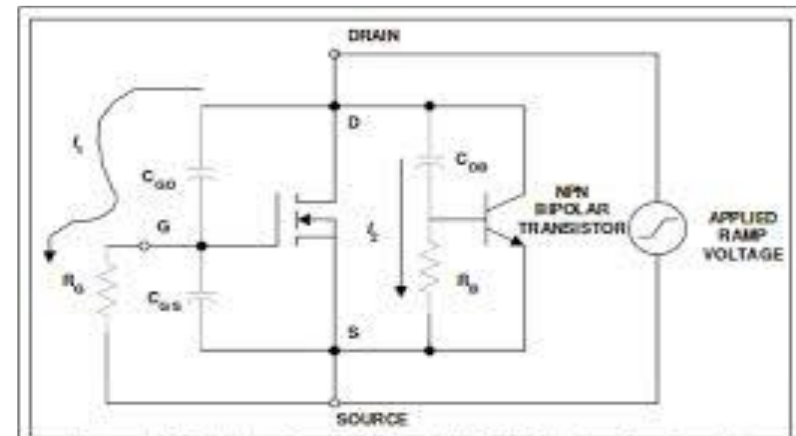
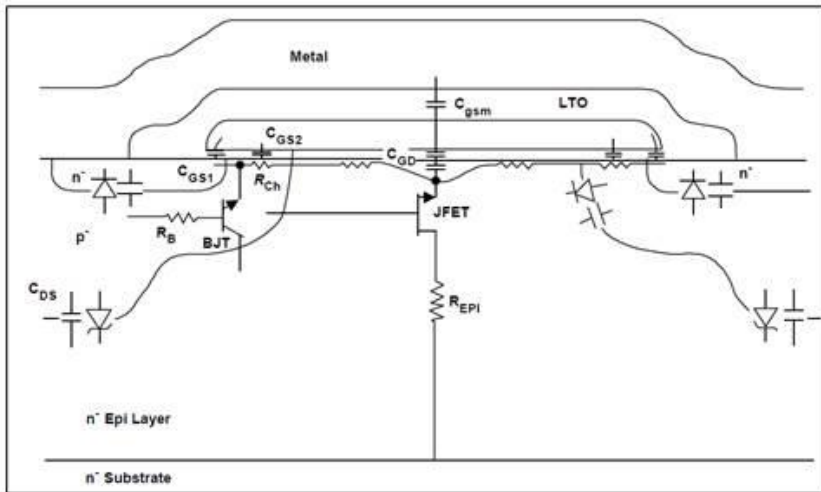
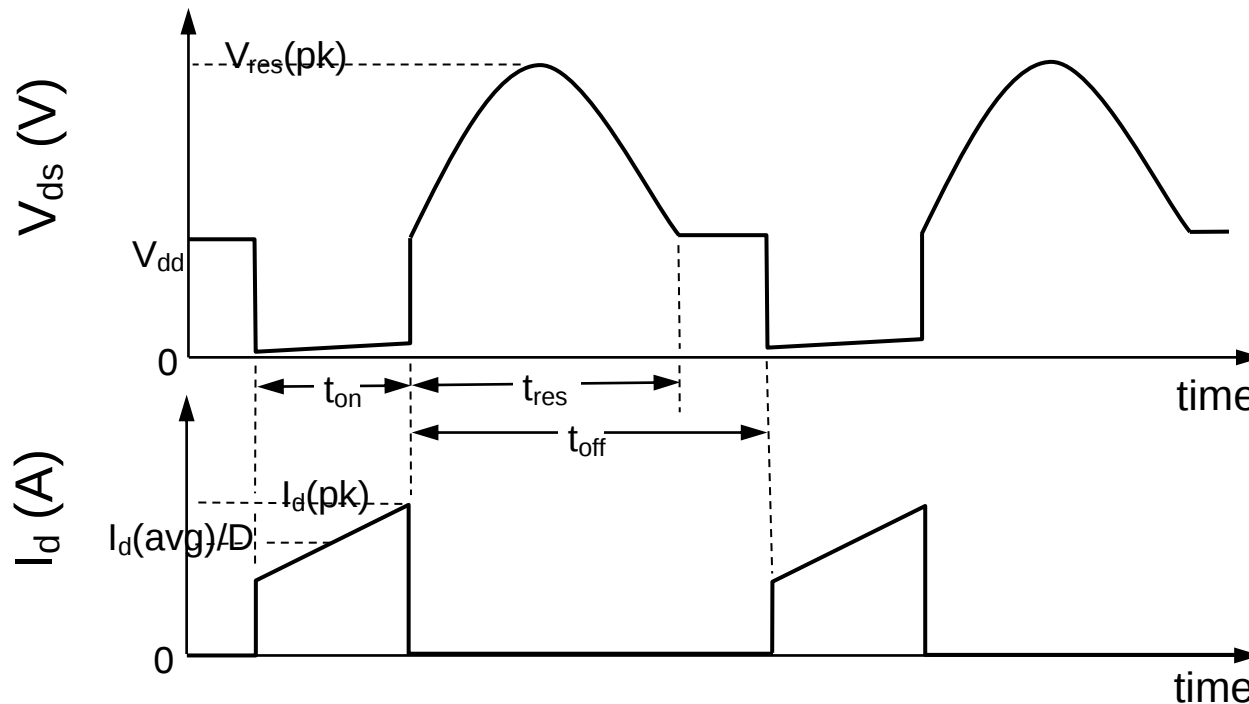


Figure 14. Equivalent Circuit of Power MOSFET Showing Two Possible Mechanisms for dV/dt Induced Turn-on.

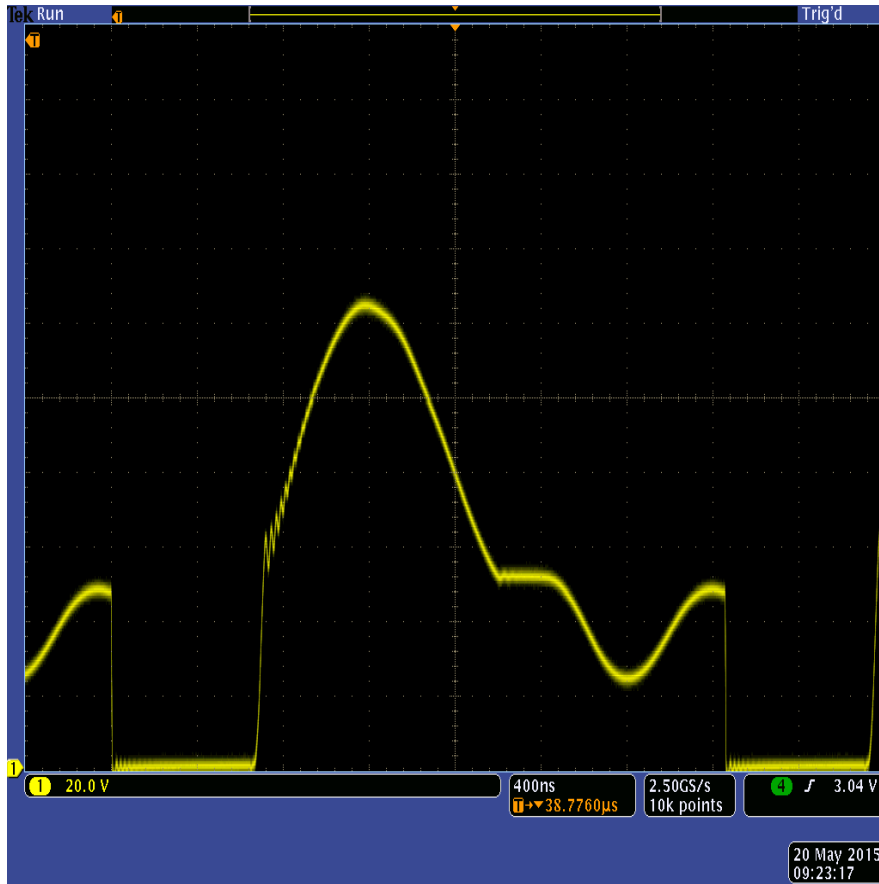
Forward Converter Design Parameters

- Duty Cycle = $D = (V_{out} / V_{in}) * (N_s / N_p) = t_{on} / t_{off}$
- $I_d(pk) = (I_d(avg) / D) + (0.5 * (V_{dd} * t_{on}) / L_m)$
- $V_{res}(pk) = V_{dd} + I_d(pk) * (L_m / C_r)^{0.5}$
- $t_{res} = \pi * (L_m * C_r)^{0.5}$
- $C_r = C_{oss} + (C_j / (N_p / N_s))$
 - C_j is the Output Schottky Junction Capacitance



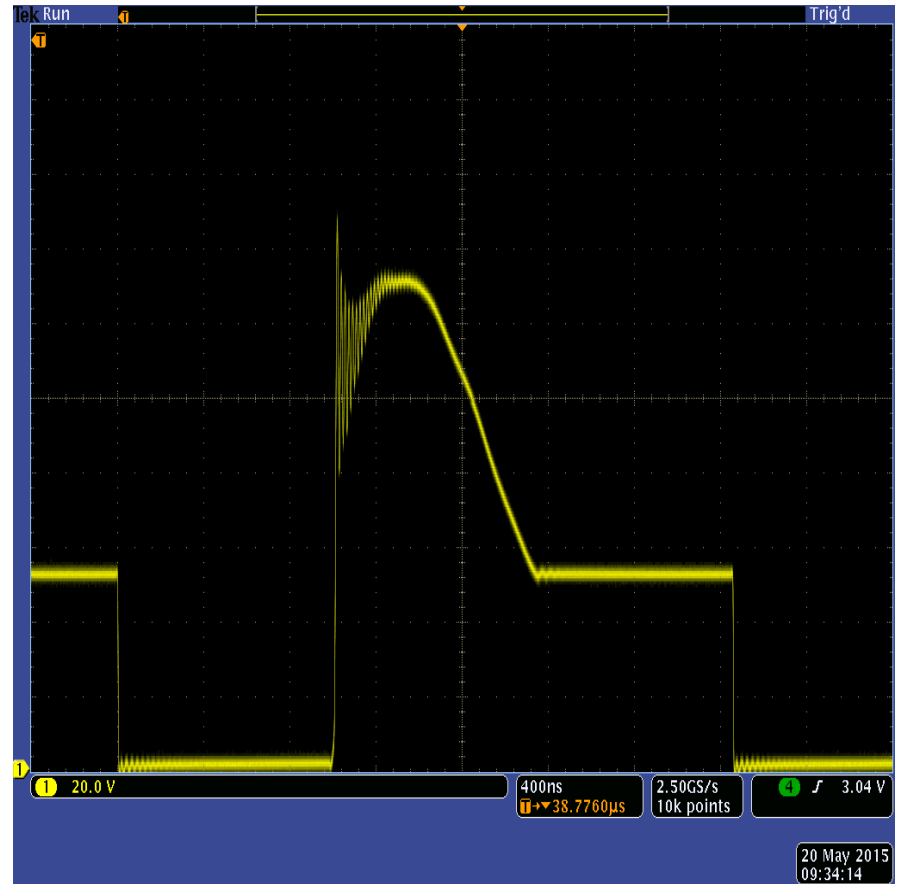
Measured Drain-Source Voltages

$V_{out} = 5.0V_{dc}$, $I_{out} = 1A_{dc}$, $f_{sw} = 350kHz$



$V_{DS(pk)} = 122V$

$V_{out} = 5.0V_{dc}$, $I_{out} = 20A_{dc}$, $f_{sw} = 350kHz$



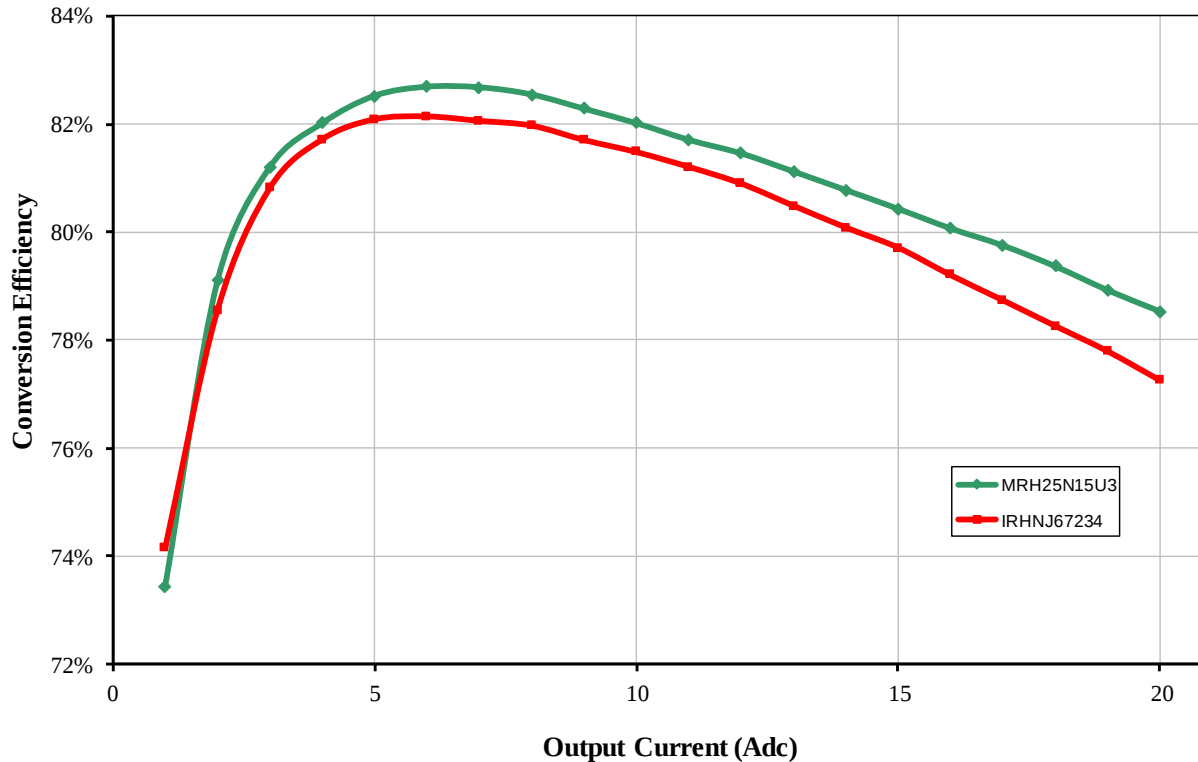
$V_{DS(pk)} = 148V$

Efficiency Parameters

- From Data Sheet Parameters:
 - $R_{ds}(ON)$
 - MRH25N15U3 – 175m Ω max.
 - IRHNJ67234 – 210m Ω max.
 - IR Device **20% Higher** Than Microsemi
 - Q_{gt}
 - MRH25N15U3 – 32nC typ. (est. 40nC max.)
 - IRHNJ67234 – 50nC max. (est. 40nC typ.)
 - C_{oss}
 - MRH25N15U3 – 275pF typ.
 - IRHNJ67234 – 187pF typ.

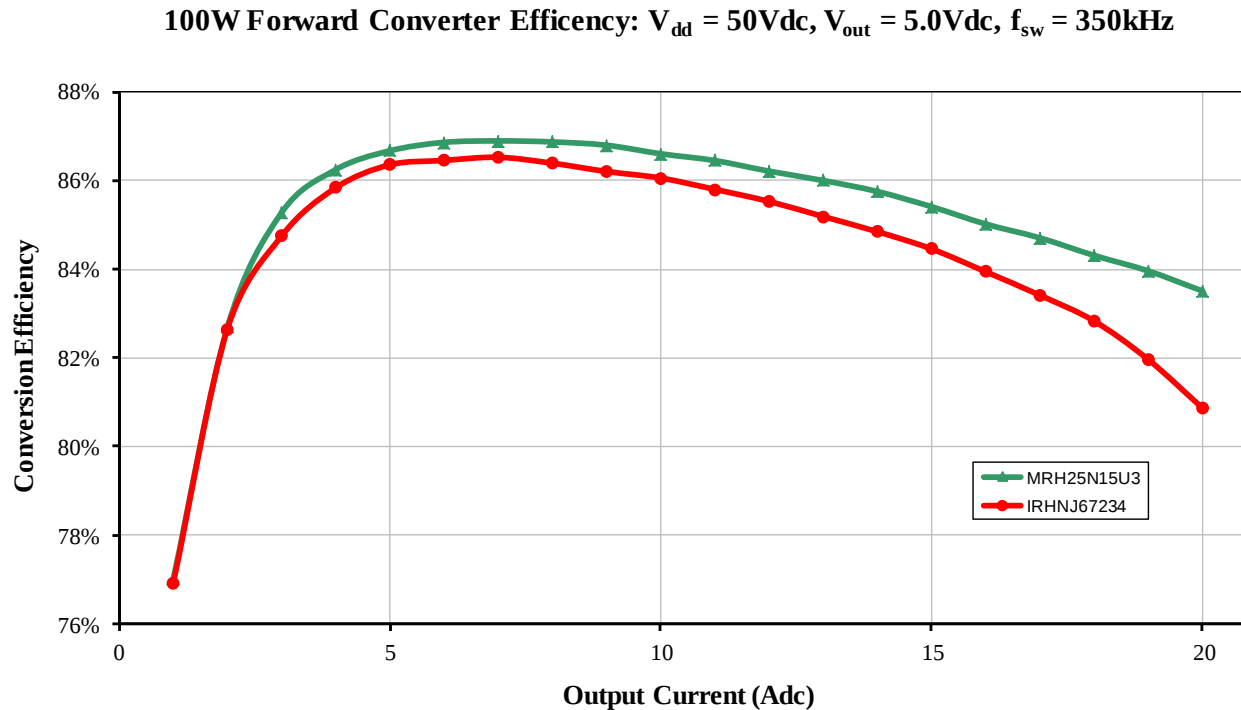
Efficiency Data- +3.3Vout, 350 Khz.

100W Forward Converter Efficiency: $V_{dd} = 50V_{dc}$, $V_{out} = 3.3V_{dc}$, $f_{sw} = 350kHz$



- At higher currents the improvement in conduction losses provide an advantage.

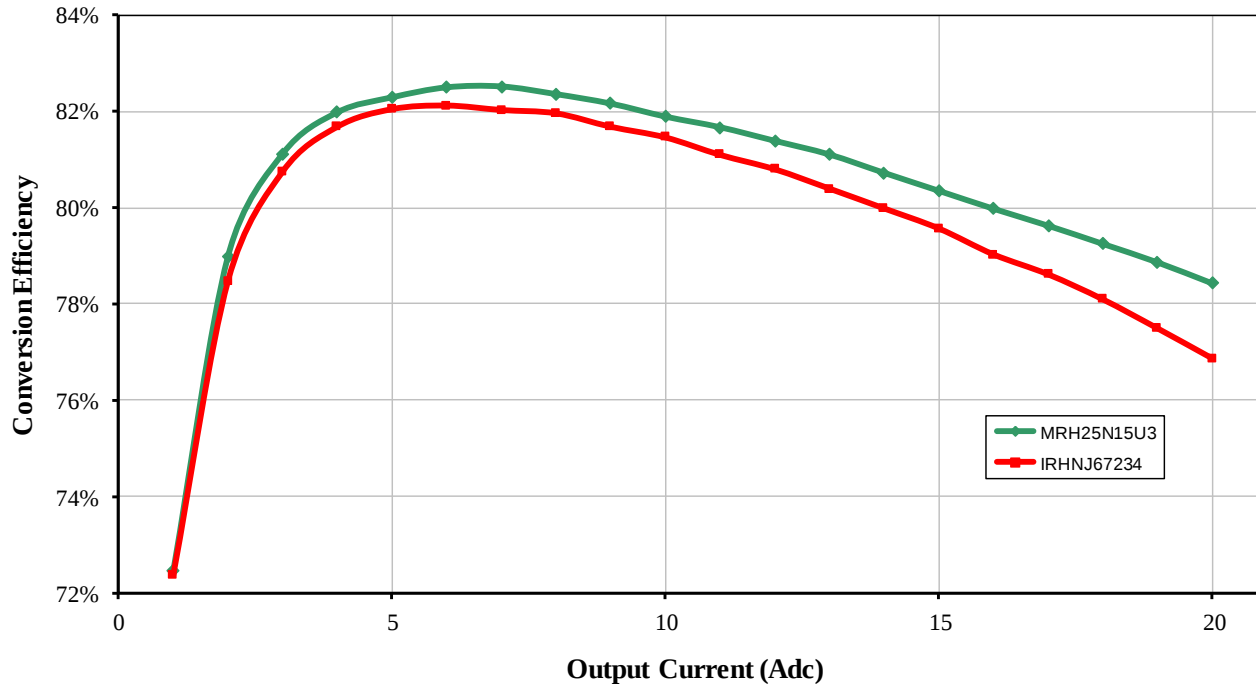
Efficiency Data, $V_{out} = 5.0V$, 350 KHz.



- At higher currents the improvement in conduction losses is slightly better at 5.0V_{out} vs. 3.3V_{out}.

Efficiency Data, +3.3Vout, 500 Khz.

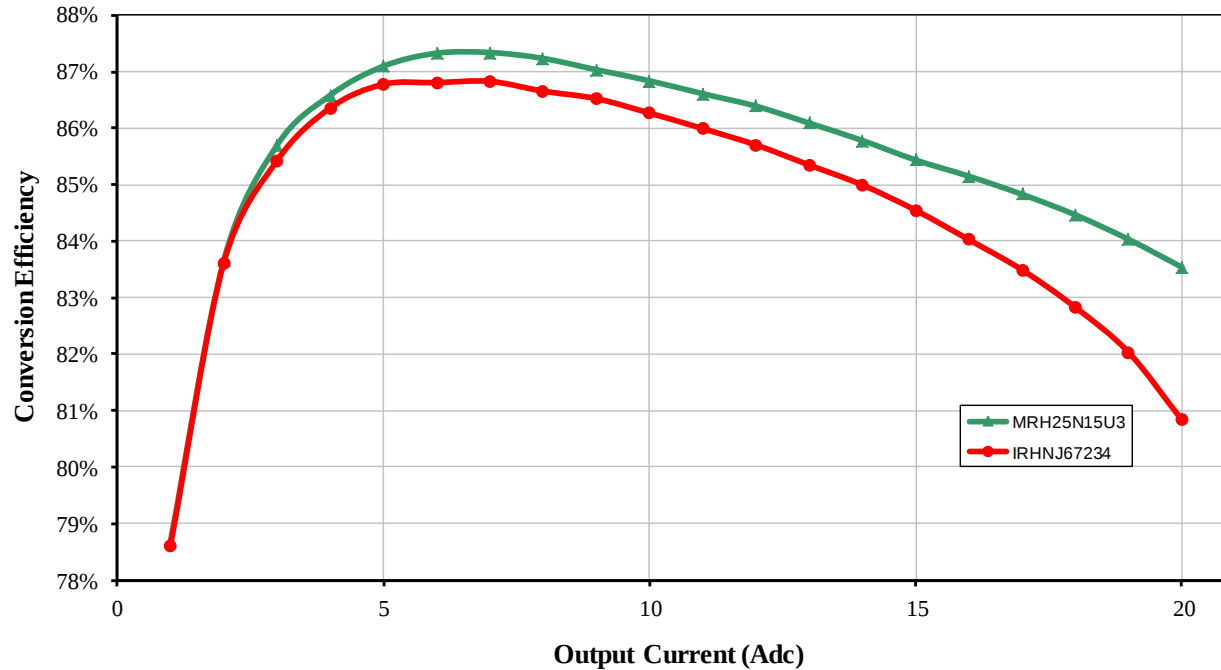
100W Forward Converter Efficiency: $V_{dd} = 50V_{dc}$, $V_{out} = 3.3V_{dc}$, $f_{sw} = 500kHz$



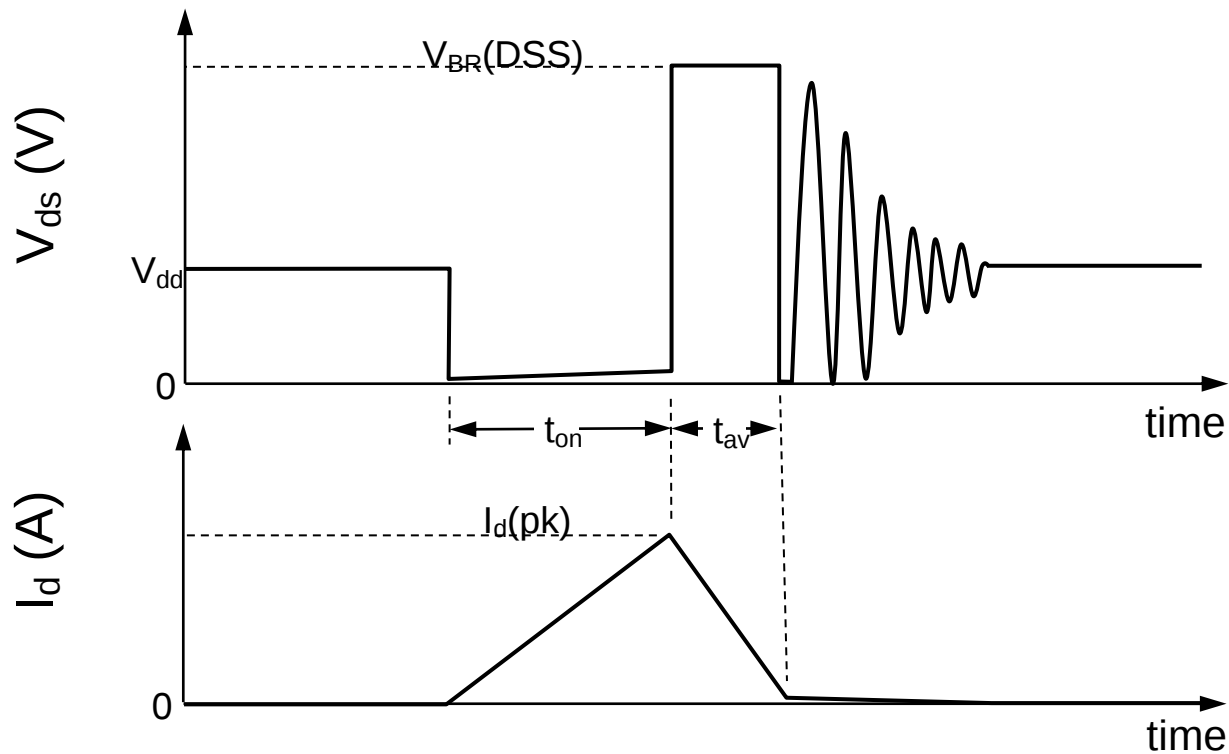
- At 500 Khz. There are more switching losses in both parts but I²MOS part maintains the advantage.

Efficiency Data, 5.0Vout, 500 Khz.

100W Forward Converter Efficiency: $V_{dd} = 50V_{dc}$, $V_{out} = 5.0V_{dc}$, $f_{sw} = 500kHz$



- Efficiency improvements @ higher currents when $V_{out} = 5.0V$

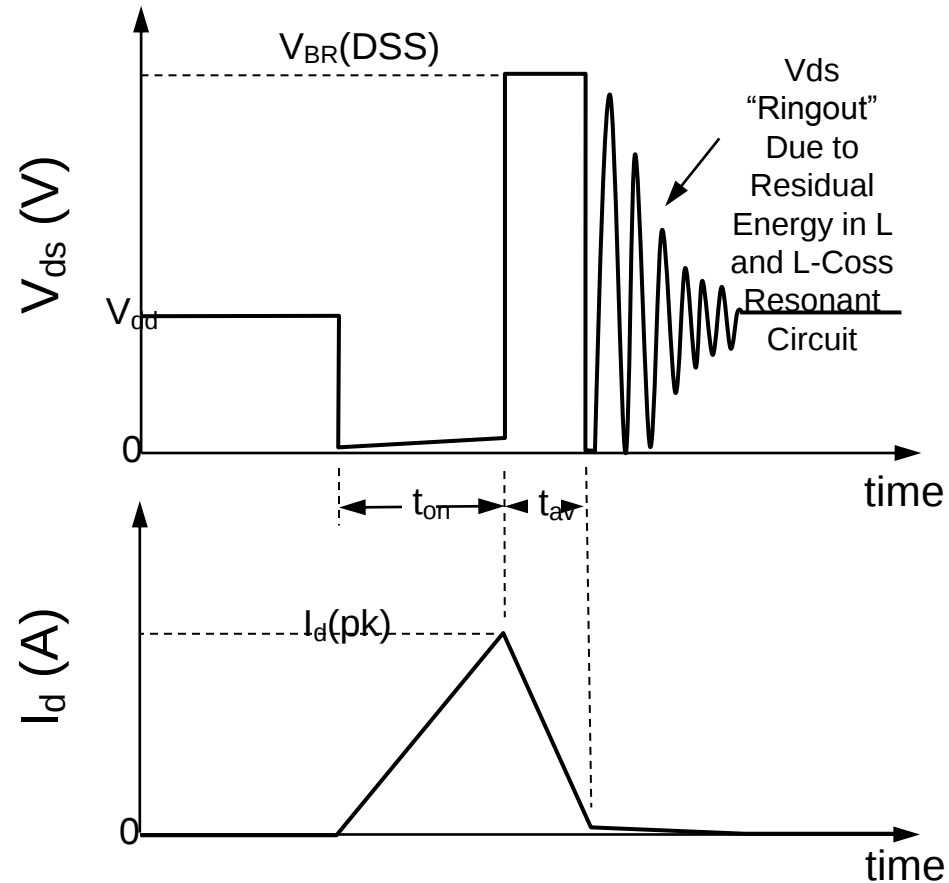


Avalanche Energy Performance

MRH25N15U3 vs. IRHNJ67234

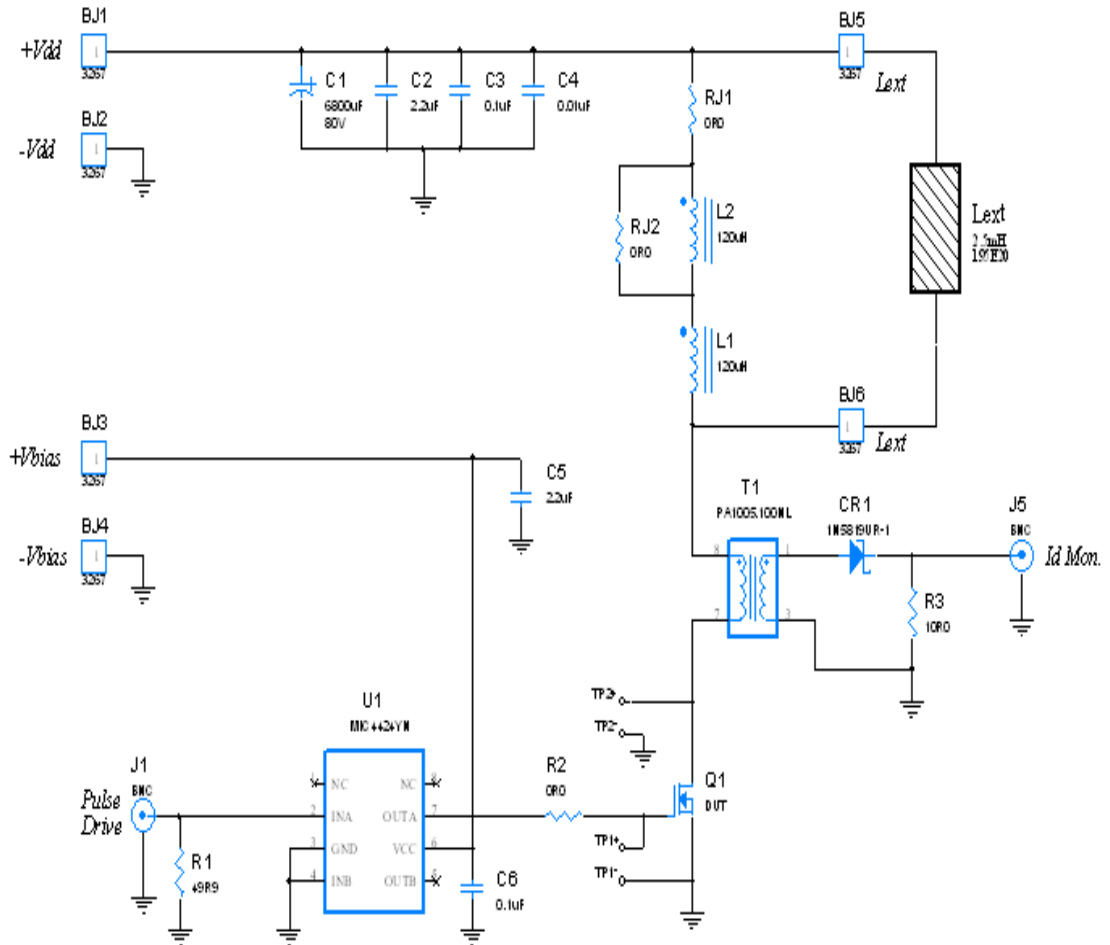
Avalanche Basics

- Avalanche Performance Indicates Ruggedness of MOSFET
 - Energy Handling Capability
 - Repetitive
 - Single Pulse
 - Specified in Joules ($V \cdot I \cdot t$)
- “Unconstrained” Inductors Cause Excursions to $V_{BR}(DSS)$
 - Energy $\sim (L \cdot I_d(pk)^2 / 2) \cdot (1 - (V_{dd} / V_{BR}(DSS)))$
 - Junction Dissipates Enormous Instantaneous Power
 - If $V_{BR}(DSS) = 250V$ and $I_d(pk) = 10A$, $P_{inst} = 2500W$!
- The Greater the Avalanche Energy Rating, The Better

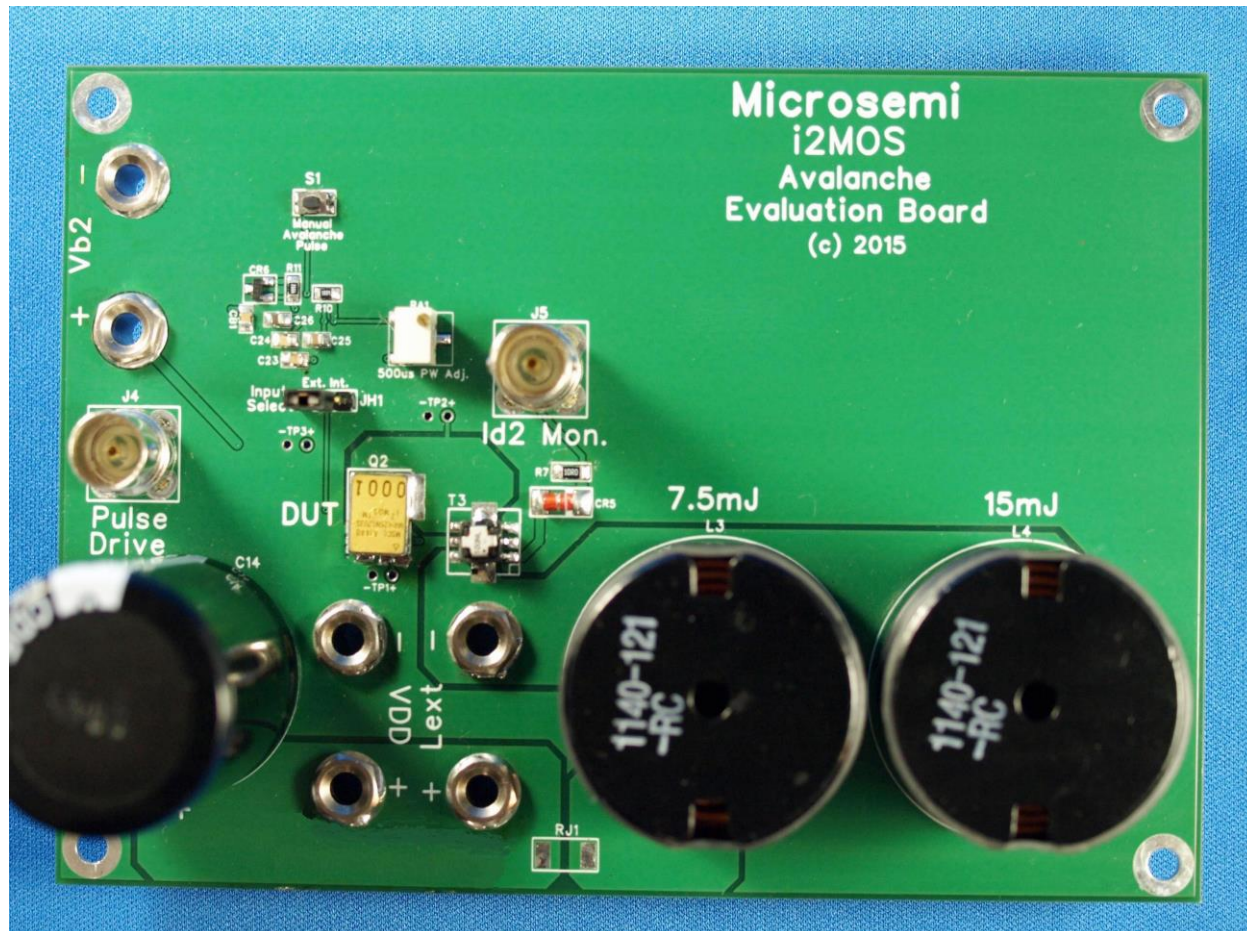


Data sheet Specs & Avalanche Test Circuit

Part #	Eas	Ear
MRH25N15U3	15 mJ	300 mJ
IRHNJ67234	7.5 mJ	56 mJ



Avalanche Test PCB



Board Size = 5.8 x 4.1 x 0.063", 4 Layer FR-4, Double Sided

Avalanche Test Procedure

Avalanche Test Has Two Regions:

1. Turn ON Device Under Test (DUT)

Ramp Inductor Current to Desired $I_d(pk)$ during ON Time (t_{on})

$$I_d(pk) = V_{dd} * t_{on} / L$$

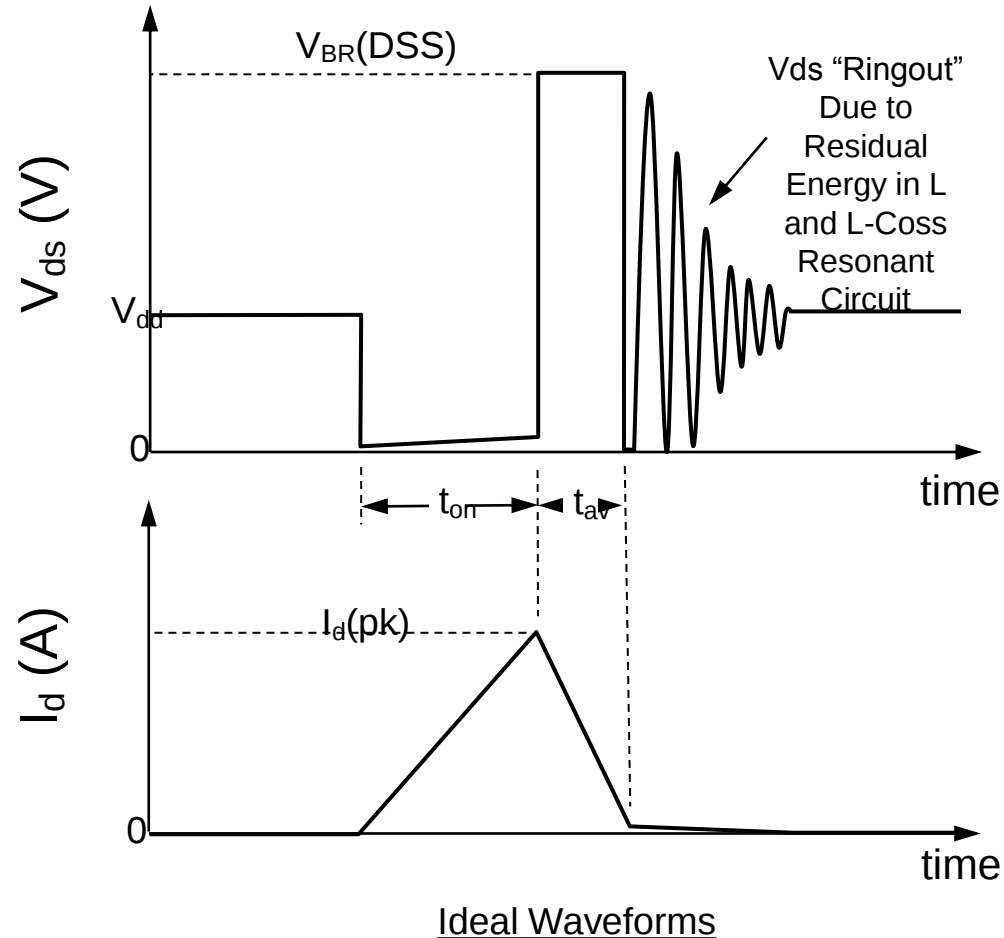
2. Turn OFF DUT

Drain Voltage “Flies” to $V_{BR}(DSS)$

$$\text{Avalanche Time } (t_{av}) = L * I_d(pk) / (V_{BR}(DSS) - V_{dd})$$

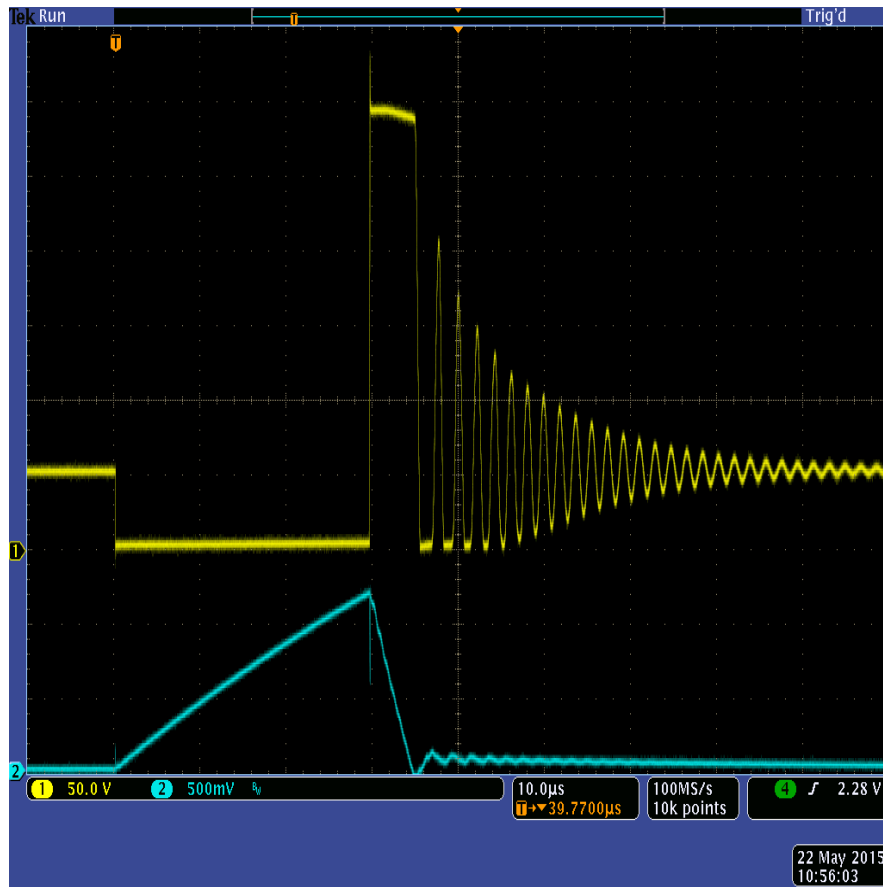
$$\text{Avalanche Energy } (E_{av}) = V_{BR}(DSS) * I_d(pk) * t_{av}$$

ON Time Adjusted to Obtain Desired $I_d(pk)$ and Thus E_{av}



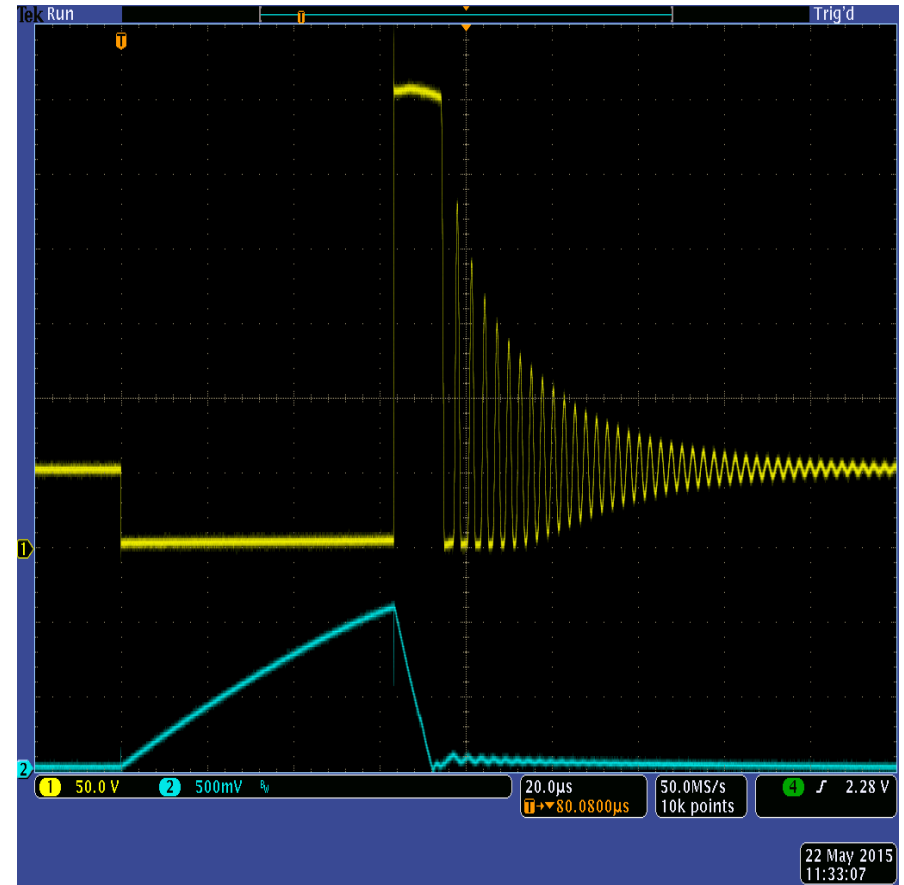
Measured Avalanche Performance

MRH25N15U3, 7.5mJ



$V_{BR}(DSS) = 283V$, $I_d(pk) = 12A$, $t_{on} = 29.5\mu s$

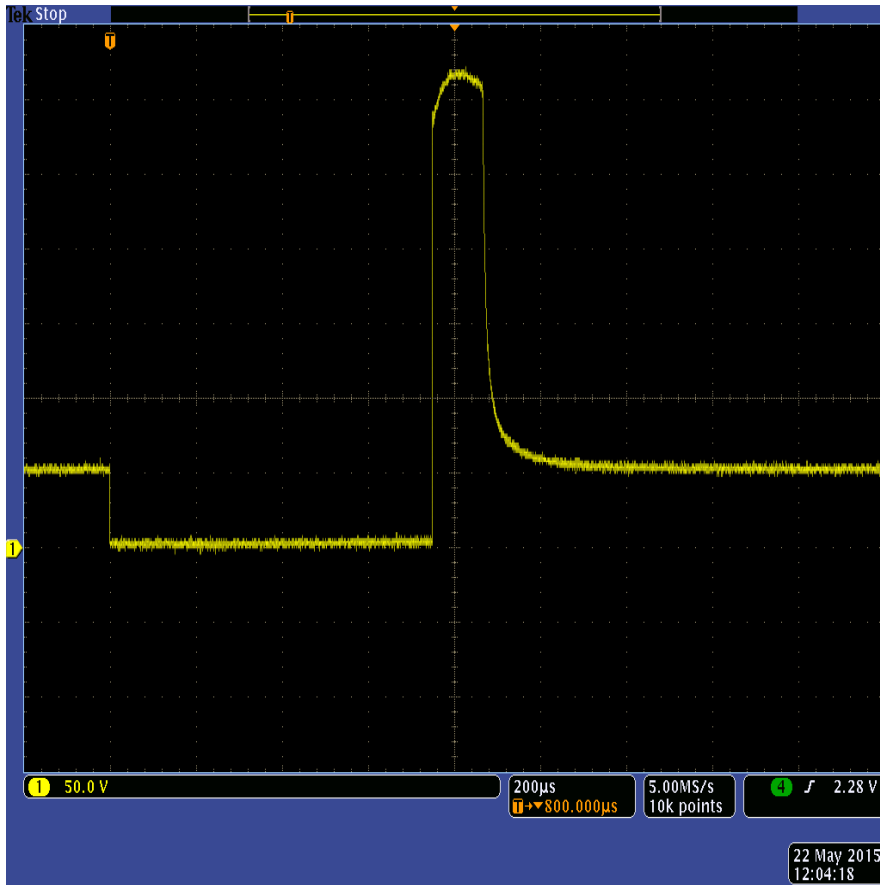
MRH25N15U3, 15mJ



$V_{BR}(DSS) = 304V$, $I_d(pk) = 11A$, $t_{on} = 71.5\mu s$

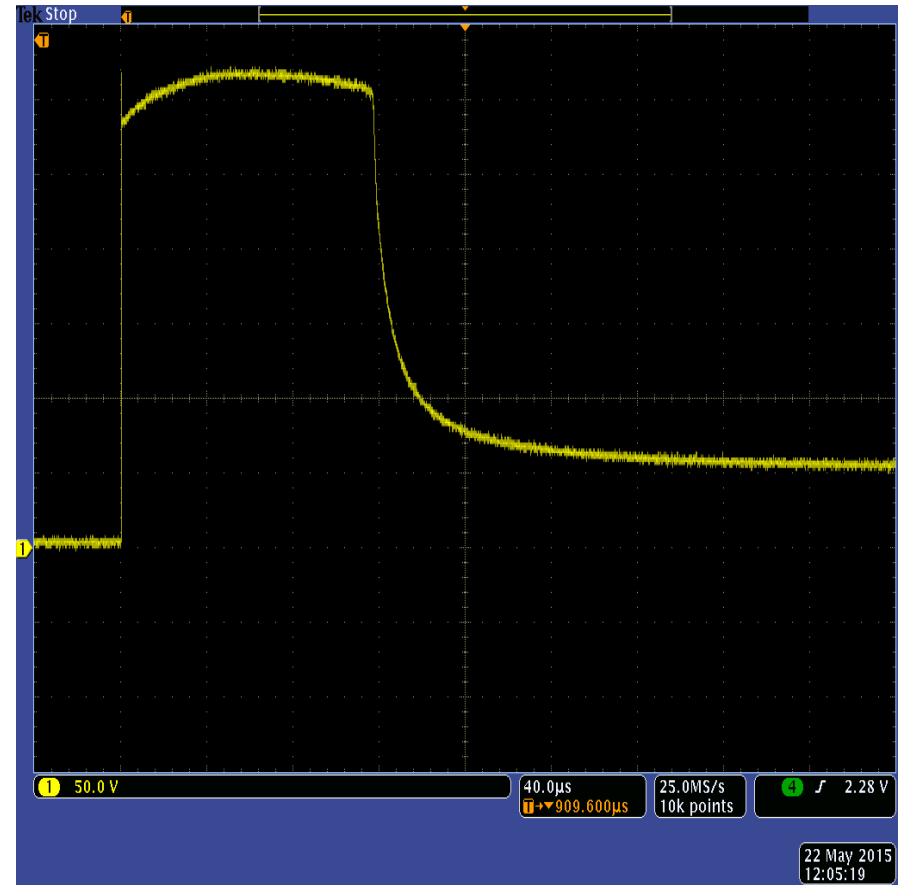
Measured Avalanche Performance

MRH25N15U3, 300mJ



$V_{BR}(DSS) = 314V$, $I_d(pk) = 15A$, $t_{on} = 750\mu s$

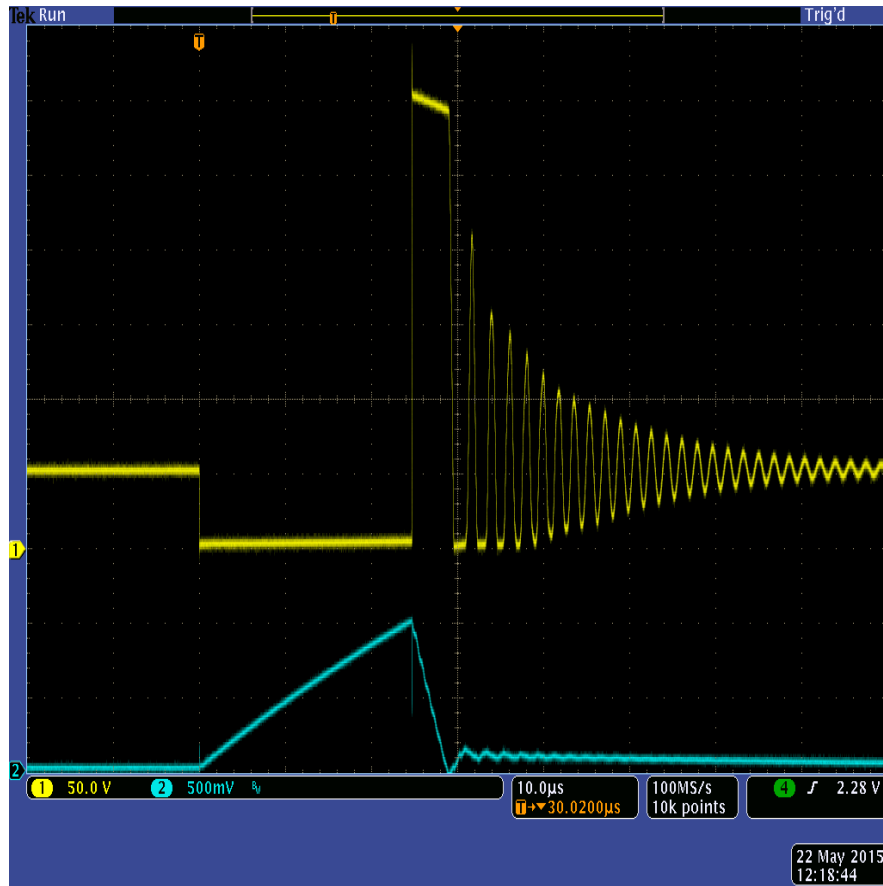
MRH25N15U3, 300mJ (Expanded)



$V_{BR}(DSS) = 314V$, $I_d(pk) = 15A$, $t_{on} = 750\mu s$

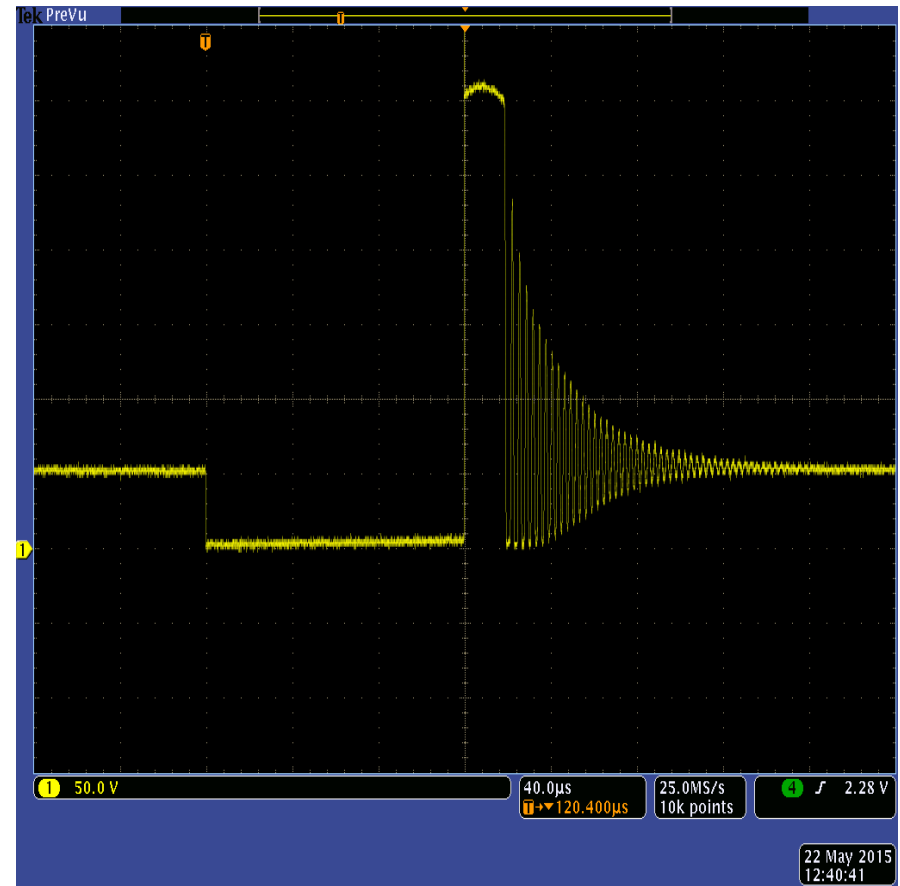
Measured Avalanche Performance

IRHNJ67234, 7.5mJ



$V_{BR}(DSS) = 300V$, $I_d(pk) = 10A$, $t_{on} = 24.5\mu s$

IRHNJ67234, 56mJ



$V_{BR}(DSS) = 302V$, $I_d(pk) = 16.7A$, $t_{on} = 120\mu s$

Summary

Efficiency

- MRH25N15U3 ***Demonstrated More Efficient*** Than IR IRHNJ67234
 - By up to 2.75%
- MGN25N15U3 Efficiency holds up over the full current range of 5A – 20A. Especially at higher load currents
- IRHNJ67234 Efficiency decreases due to higher conduction Losses
 - Useful Output Current Range Must Be De-Rated to 18A
- Increased Losses Mean More Aggressive Thermal Management Required (Bigger Heat Sink for Lower θ_{JA})

Avalanche Capability

- Microsemi MRH25N15U3 **Demonstrated 2X Repetitive Avalanche Capability** Over IR IRHNJ67234
- Microsemi MRH25N15U3 **Demonstrated 5.4X Single Event Avalanche Capability** Over IR IRHNJ67234



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Thank You



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